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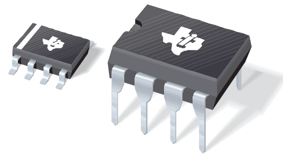


EXTENDED COMMON-MODE RS-485 TRANSCEIVERS

FEATURES

- **Common-Mode Voltage Range (−20 V to 25 V) More Than Doubles TIA/EIA-485 Requirement**
- **Receiver Equalization Extends Cable Length, Signaling Rate (HVD23, HVD24)**
- **Reduced Unit-Load for up to 256 Nodes**
- **Bus I/O Protection to Over 16-kV HBM**
- **Failsafe Receiver for Open-Circuit, Short-Circuit and Idle-Bus Conditions**
- **Low Standby Supply Current 1-μA Max**
- **More Than 100 mV Receiver Hysteresis**

APPLICATIONS

- **Long Cable Solutions**
  - **Factory Automation**
  - **Security Networks**
  - **Building HVAC**
- **Severe Electrical Environments**
  - **Electrical Power Inverters**
  - **Industrial Drives**
  - **Avionics**

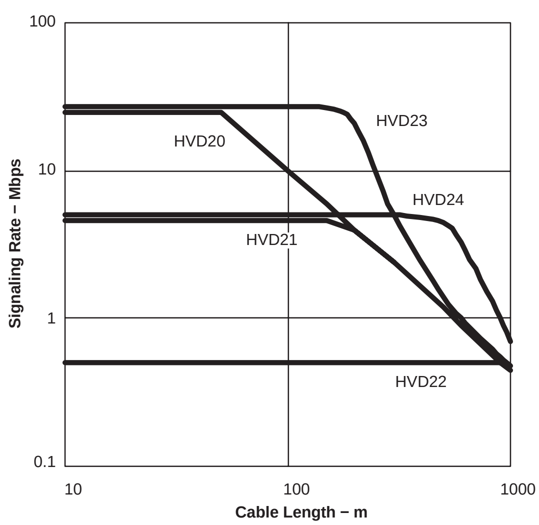
DESCRIPTION

The transceivers in the HVD2x family offer performance far exceeding typical RS−485 devices. In addition to meeting all requirements of the TIA/EIA−485−A standard, the HVD2x family operates over an extended range of common-mode voltage, and has features such as high ESD protection, wide receiver hysteresis, and failsafe operation. This family of devices is ideally suited for long-cable networks, and other applications where the environment is too harsh for ordinary transceivers.

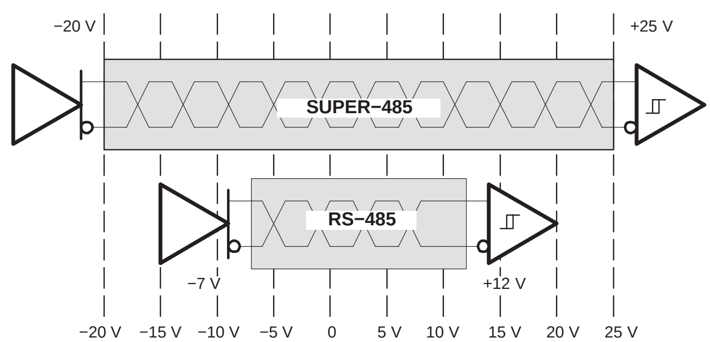
These devices are designed for bidirectional data transmission on multipoint twisted-pair cables. Example applications are digital motor controllers, remote sensors and terminals, industrial process control, security stations, and environmental control systems.

These devices combine a 3-state differential driver and a differential receiver, which operate from a single 5-V power supply. The driver differential outputs and the receiver differential inputs are connected internally to form a differential bus port that offers minimum loading to the bus. This port features an extended common-mode voltage range making the device suitable for multipoint applications over long cable runs.

HVD2x APPLICATION SPACE



HVD2x Devices Operate Over a Wider Common-Mode Voltage Range



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION (continued)

The ‘HVD20 provides high signaling rate (up to 25 Mbps) for interconnecting networks of up to 64 nodes.

The ‘HVD21 allows up to 256 connected nodes at moderate data rates (up to 5 Mbps). The driver output slew rate is controlled to provide reliable switching with shaped transitions which reduce high-frequency noise emissions.

The ‘HVD22 has controlled driver output slew rate for low radiated noise in emission-sensitive applications and for improved signal quality with long stubs. Up to 256 ‘HVD22 nodes can be connected at signaling rates up to 500 kbps.

The ‘HVD23 implements receiver equalization technology for improved jitter performance on differential bus applications with data rates up to 25 Mbps at cable lengths up to 160 meters.

The ‘HVD24 implements receiver equalization technology for improved jitter performance on differential bus applications with data rates in the range of 1 Mbps to 10 Mbps at cable lengths up to 1000 meters.

The receivers also include a failsafe circuit that provides a high-level output within 250 microseconds after loss of the input signal. The most common causes of signal loss are disconnected cables, shorted lines, or the absence of any active transmitters on the bus. This feature prevents noise from being received as valid data under these fault conditions. This feature may also be used for Wired-Or bus signaling.

The SN65HVD2X devices are characterized for operation over the temperature range of −40°C to 85°C.

PRODUCT SELECTION GUIDE

PART NUMBERS	CABLE LENGTH AND SIGNALING RATE(1)	NODES	MARKING
SN65HVD20	Up to 50 m at 25 Mbps	Up to 64	D: VP20 P: 65HVD20
SN65HVD21	Up to 150 m at 5 Mbps (with slew rate limit)	Up to 256	D: VP21 P: 65HVD21
SN65HVD22	Up to1200 m at 500 kbps (with slew rate limit)	Up to 256	D: VP22 P: 65HVD22
SN65HVD23	Up to 160 m at 25 Mbps (with receiver equalization)	Up to 64	D: VP23 P: 65HVD23
SN65HVD24	Up to 500 m at 3 Mbps (with receiver equalization)	Up to 256	D: VP24 P: 65HVD24

(1) Distance and signaling rate predictions based upon Belden 3105A cable and 15% eye pattern jitter.

AVAILABLE OPTIONS

PLASTIC THROUGH-HOLE P−PACKAGE (JEDEC MS-001)	PLASTIC SMALL-OUTLINE(1) D−PACKAGE (JEDEC MS-012)
SN65HVD20P SN65HVD21P SN65HVD22P SN65HVD23P SN65HVD24P	SN65HVD20D SN65HVD21D SN65HVD22D SN65HVD23D SN65HVD24D

(1) Add R suffix for taped and reeled carriers.

DRIVER FUNCTION TABLE

HVD20, HVD21, HVD22				HVD23, HVD24			
INPUT	ENABLE	OUTPUTS		INPUT	ENABLE	OUTPUTS	
D	DE	A	B	D	DE	A	B
H	H	H	L	H	H	H	L
L	H	L	H	L	H	L	H
X	L	Z	Z	X	L	Z	Z
X	OPEN	Z	Z	X	OPEN	Z	Z
OPEN	H	H	L	OPEN	H	L	H

H = high level, L= low level, X = don’t care, Z = high impedance (off), ? = indeterminate

RECEIVER FUNCTION TABLE

DIFFERENTIAL INPUT $V_{ID} = (V_A - V_B)$	ENABLE $\overline{RE}$	OUTPUT R
$0.2\ V \leq V_{ID}$	L	H
$-0.2\ V < V_{ID} < 0.2\ V$	L	H (see Note A)
$V_{ID} \leq -0.2\ V$	L	L
X	H	Z
X	OPEN	Z
Open circuit	L	H
Short Circuit	L	H
Idle (terminated) bus	L	H

H = high level, L= low level, Z = high impedance (off)

NOTE A: If the differential input V_{ID} remains within the transition range for more than 250 µs, the integrated failsafe circuitry detects a bus fault, and set the receiver output to a high state. See Figure 15.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted[(1)]

			SN65HVD2X
Supply voltage[(2)], V_{CC}			−0.5 V to 7 V
Voltage at any bus I/O terminal			−27 V to 27 V
Voltage input, transient pulse, A and B, (through 100 Ω, see Figure 16)			−60 V to 60 V
Voltage input at any D, DE or $\overline{RE}$ terminal			−0.5 V to V_{CC}+ 0.5 V
Receiver output current, I_O			−10 mA to 10 mA
Electrostatic discharge	Human Body Model[(3)]	A, B, GND	16 kV
		All pins	5 kV
	Charged-Device Model[(4)]	All pins	1.5 kV
	Machine Model[(5)]	All pins	200 V
Continuous total power dissipation			See Power Dissipation Rating Table
Junction temperature, T_J			150°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
(3) Tested in accordance with JEDEC Standard 22, Test Method A114-A.
(4) Tested in accordance with JEDEC Standard 22, Test Method C101.
(5) Tested in accordance with JEDEC Standard 22, Test Method A115-A.

POWER DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR(3) ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
D	Low-K(1)	577 mW	4.62 mW/°C	369 mW	300 mW
	High-K(2)	913 mW	7.3 mW/°C	584 mW	474 mW
P	Low-K(1)	984 mW	7.87 mW/°C	630 mW	512 mW
	High-K(2)	1344 mW	10.8 mW/°C	860 mW	700 mW

(1) In accordance with the Low-K thermal metric definitions of EIA/JESD51−3.
(2) In accordance with the High-K thermal metric definitions of EIA/JESD51−7.
(3) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

THERMAL CHARACTERISTICS

PARAMETER				TEST CONDITIONS		VALUE	UNITS
θ_{JB}	Junction-to-board thermal resistance		D			86.2	°C/W
			P			56	
θ_{JC}	Junction-to-case thermal resistance		D			47.1	
			P			54	
P_D	Device power dissipation	Typical	HVD20	V_{CC} = 5 V, T_J = 25°C, R_L = 54 Ω, C_L = 50 pF (driver), C_L = 15 pF (receiver), 50% Duty cycle square-wave signal, Driver and receiver enabled	25 Mbps	295	mW
			HVD21		5 Mbps	260	
			HVD22		500 kbps	233	
			HVD23		25 Mbps	302	
			HVD24		5 Mbps	267	
		Worst case	HVD20	V_{CC} = 5.5 V, T_J = 125°C, R_L = 54 Ω, C_L = 50 pF, C_L = 15 pF (receiver), 50% Duty cycle square-wave signal, Driver and receiver enabled	25 Mbps	408	
			HVD21		5 Mbps	342	
			HVD22		500 kbps	300	
			HVD23		25 Mbps	417	
			HVD24		5 Mbps	352	
T_{SD}	Thermal shut-down junction temperature					170	°C

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.5	5	5.5	V
Voltage at any bus I/O terminal	A, B	−20		25	V
High-level input voltage, V_{IH}	D, DE, $\overline{RE}$	2		V_{CC}	V
Low-level input voltage, V_{IL}	D, DE, $\overline{RE}$	0		0.8	V
Differential input voltage, V_{ID}	A with respect to B	−25		25	V
Output current	Driver	−110		110	mA
	Receiver	−8		8	mA
Operating free-air temperature, T_A(1)		−40		85	°C
Junction temperature, T_J		−40		130	°C

(1) Maximum free-air temperature operation is allowed as long as the device recommended junction temperature is not exceeded.

DRIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
V_{IK}	Input clamp voltage	$I_I = -18$ mA		−1.5	0.75		V
V_O	Open-circuit output voltage	A or B, No load		0		V_{CC}	V
$\|V_{OD(SS)}\|$	Steady-state differential output voltage magnitude	No load (open circuit)		3.3	4.2	V_{CC}	V
		$R_L = 54\ \Omega$,	See Figure 1	1.8	2.5		
		With common-mode loading,	See Figure 2	1.8			
$\Delta\|V_{OD(SS)}\|$	Change in steady-state differential output voltage between logic states	See Figure 1 and Figure 3		−0.1		0.1	V
$V_{OC(SS)}$	Steady-state common-mode output voltage	See Figure 1		2.1	2.5	2.9	V
$\Delta V_{OC(SS)}$	Change in steady-state common-mode output voltage, $V_{OC(H)} - V_{OC(L)}$	See Figure 1 and Figure 4		−0.1		0.1	V
$V_{OC(PP)}$	Peak-to-peak common-mode output voltage, $V_{OC(MAX)} - V_{OC(MIN)}$	$R_L = 54\ \Omega$, $C_L = 50$ pF, See Figure 1 and Figure 4			0.35		V
$V_{OD(RING)}$	Differential output voltage over and under shoot	$R_L = 54\ \Omega$, $C_L = 50$ pF, See Figure 5				10%	
I_I	Input current	D, DE		−100		100	µA
$I_{O(OFF)}$	Output current with power off	V_{CC} < = 2.5 V		See receiver line input current			
I_{OZ}	High impedance state output current	DE at 0 V					
I_{OS}	Short-circuit output current	$V_O = -20$ V to 25 V,	See Figure 9	−250		250	mA
C_{OD}	Differential output capacitance			See receiver C_I			

(1) All typical values are at V_{CC} = 5 V and 25°C.

DRIVER SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
t_{PLH}	Differential output propagation delay, low-to- high	$R_L = 54\ \Omega$, $C_L = 50$ pF, See Figure 3	HVD20, HVD23	6	10	20	ns
t_{PHL}	Differential output propagation delay, high-to-low		HVD21, HVD24	20	32	60	
			HVD22	160	280	500	
t_r	Differential output rise time	$R_L = 54\ \Omega$, $C_L = 50$ pF, See Figure 3	HVD20, HVD23	2	6	12	ns
t_f	Differential output fall time		HVD21, HVD24	20	40	60	
			HVD22	200	400	600	
t_{PZH}	Propagation delay time, high-impedance-to-high-level output	$\overline{RE}$ at 0 V, See Figure 6	HVD20, HVD23			40	ns
t_{PHZ}	Propagation delay time, high-level-output-to-high-impedance		HVD21, HVD24			100	
			HVD22			300	
t_{PZL}	Propagation delay time, high-impedance-to-low-level output	$\overline{RE}$ at 0 V, See Figure 7	HVD20, HVD23			40	ns
t_{PLZ}	Propagation delay time, low-level-output-to-high-impedance		HVD21, HVD24			100	
			HVD22			300	
$t_{d(standby)}$	Time from an active differential output to standby	$\overline{RE}$ at V_{CC}, See Figure 8				2	µs
$t_{d(wake)}$	Wake-up time from standby to an active differential output					8	µs
$t_{sk(p)}$	Pulse skew $\|t_{PLH} - t_{PHL}\|$	HVD20, HVD23				2	ns
		HVD21, HVD24				6	
		HVD22				50	

(1) All typical values are at V_{CC} = 5 V and 25°C.

RECEIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP[1]	MAX	UNIT
$V_{IT(+)}$	Positive-going differential input voltage threshold	See Figure 10	V_O = 2.4 V, I_O = −8 mA		60	200	mV
$V_{IT(-)}$	Negative-going differential input voltage threshold		V_O = 0.4 V, I_O = 8 mA	−200	−60		
V_{HYS}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)			100	130		mV
$V_{IT(F+)}$	Positive-going differential input failsafe voltage threshold	See Figure 15	V_{CM} = −7 V to 12 V	40	120	200	mV
			V_{CM} = −20 V to 25 V		120	250	
$V_{IT(F-)}$	Negative-going differential input failsafe voltage threshold	See Figure 15	V_{CM} = −7 V to 12 V	−200	−120	−40	mV
			V_{CM} = −20 V to 25 V	−250	−120		
V_{IK}	Input clamp voltage	I_I = −18 mA		−1.5			V
V_{OH}	High-level output voltage	V_{ID} = 200 mV, I_{OH} = −8 mA, See Figure 11		4			V
V_{OL}	Low-level output voltage	V_{ID} = −200 mV, I_{OL} = 8 mA, See Figure 11				0.4	V
$I_{I(BUS)}$	Bus input current (power on or power off)	V_I = −7 to 12 V, Other input = 0 V	HVD20, HVD23	−400		500	μA
			HVD21, HVD22, HVD24	−100		125	
		V_I = −20 to 25 V, Other input = 0 V	HVD20, HVD23	−800		1000	
			HVD21, HVD22, HVD24	−200		250	
I_I	Input current	$\overline{RE}$		−100		100	μA
R_I	Input resistance	HVD20, 23		24			kΩ
		HVD21, 22, 24		96			
C_{ID}	Differential input capacitance	V_{ID} = 0.5 + 0.4 sine (2π x 1.5 x 10^6t)				20	pF

(1) All typical values are at 25°C.

RECEIVER SWITCHING CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high level output	See Figure 11	HVD20, HVD23		16	35	ns
t_{PHL}	Propagation delay time, high-to-low level output		HVD21, HVD22, HVD24		25	50	
t_r	Receiver output rise time	See Figure 11			2	4	ns
t_f	Receiver output fall time						
t_{PZH}	Receiver output enable time to high level	See Figure 12			90	120	ns
t_{PHZ}	Receiver output disable time from high level				16	35	
t_{PZL}	Receiver output enable time to low level	See Figure 13			90	120	ns
t_{PLZ}	Receiver output disable time from low level				16	35	
$t_{r(standby)}$	Time from an active receiver output to standby	See Figure 14, DE at 0 V				2	μs
$t_{r(wake)}$	Wake-up time from standby to an active receiver output					8	
$t_{sk(p)}$	Pulse skew | $t_{PLH} - t_{PHL}$ |					5	ns
$t_{p(set)}$	Delay time, bus fail to failsafe set	See Figure 15, pulse rate = 1 kHz			250	350	μs
$t_{p(reset)}$	Delay time, bus recovery to failsafe reset					50	ns

RECEIVER EQUALIZATION CHARACTERISTICS(1)

over recommended operating conditions

PARAMETER		TEST CONDITIONS				MIN	TYP(2)	MAX	UNIT
$t_{j(pp)}$	Peak-to-peak eye-pattern jitter	Pseudo-random NRZ code with a bit pattern length of $2^{16} - 1$, Beldon 3105A cable, See Figure 27	25 Mbps	0 m	HVD23		2		ns
				100 m	HVD20		6		
					HVD23		3		
				150 m	HVD20		15		
					HVD23		4		
				200 m	HVD20		27		
					HVD23		8		
			10 Mbps	200 m	HVD20		22		
					HVD23		8		
				250 m	HVD20		34		
					HVD23		15		
				300 m	HVD20		49		
					HVD23		27		
			5 Mbps	500 m	HVD21		128		
					HVD24		18		
			3 Mbps	500 m	HVD20		93		
					HVD21		103		
					HVD23		90		
					HVD24		16		
			1 Mbps	1000 m	HVD21		216		
					HVD24		62		

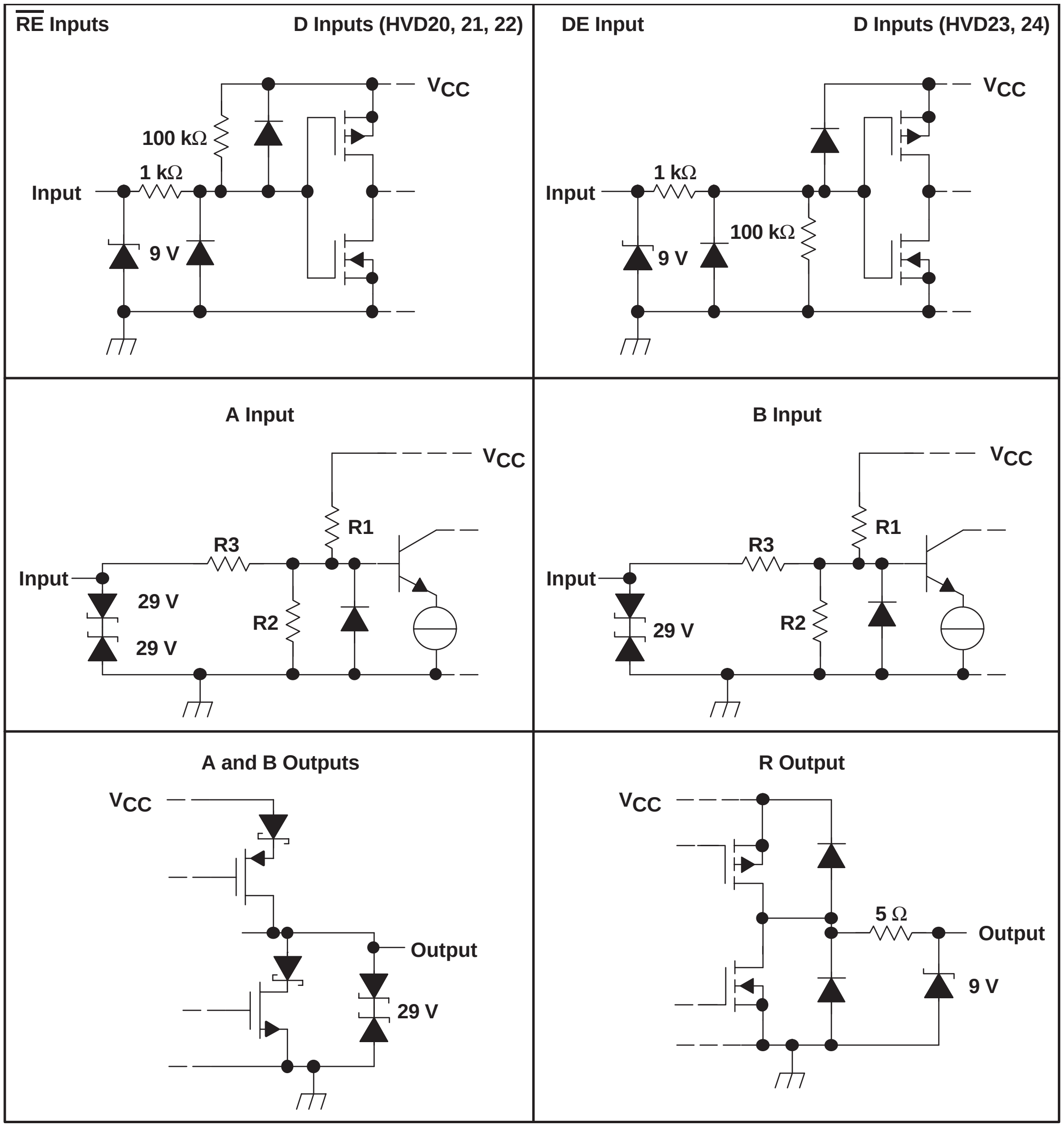
(1) The HVD20 and HVD21 do not have receiver equalization, but are specified for comparison.
(2) All typical values are at V_{CC} = 5 V, and temperature = 25°C.

SUPPLY CURRENT

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{CC}	Supply current	Driver enabled (DE at V_{CC}), Receiver enabled (RE at 0 V) No load, V_I = 0 V or V_{CC}	HVD20		6	9	mA
			HVD21		8	12	
			HVD22		6	9	
			HVD23		7	11	
			HVD24		10	14	
		Driver enabled (DE at V_{CC}), Receiver disabled (RE at V_{CC}) No load, V_I = 0 V or V_{CC}	HVD20		5	8	mA
			HVD21		7	11	
			HVD22		5	8	
			HVD23		5	9	
			HVD24		8	12	
		Driver disabled (DE at 0 V), Receiver enabled (RE at 0 V) No load	HVD20		4	7	mA
			HVD21		5	8	
			HVD22		4	7	
			HVD23		4.5	9	
			HVD24		5.5	10	
		Driver disabled (DE at 0 V), Receiver disabled (RE at V_{CC}) D open	All HVD2x			1	µA

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



	R1/R2	R3
HVD20, 23	9 kΩ	45 kΩ
HVD21, 22, 24	36 kΩ	180 kΩ

PARAMETER MEASUREMENT INFORMATION

NOTES:
Test load capacitance includes probe and jig capacitance (unless otherwise specified).
Signal generator characteristics: rise and fall time < 6 ns, pulse rate 100 kHz, 50% duty cycle, Z_O = 50 Ω (unless otherwise specified)

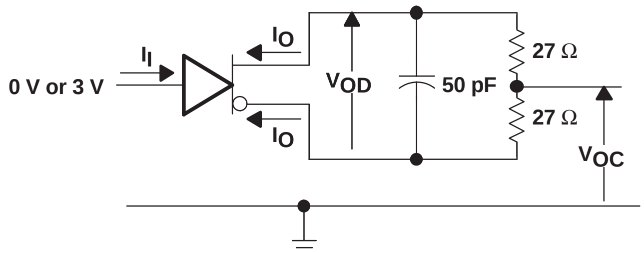


Figure 1. Driver Test Circuit, V_{OD} and V_{OC} Without Common-Mode Loading

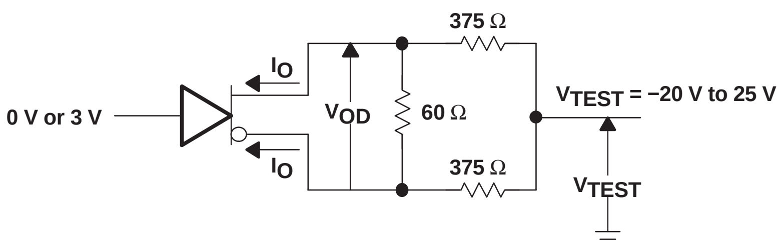


Figure 2. Driver Test Circuit, V_{OD} With Common-Mode Loading

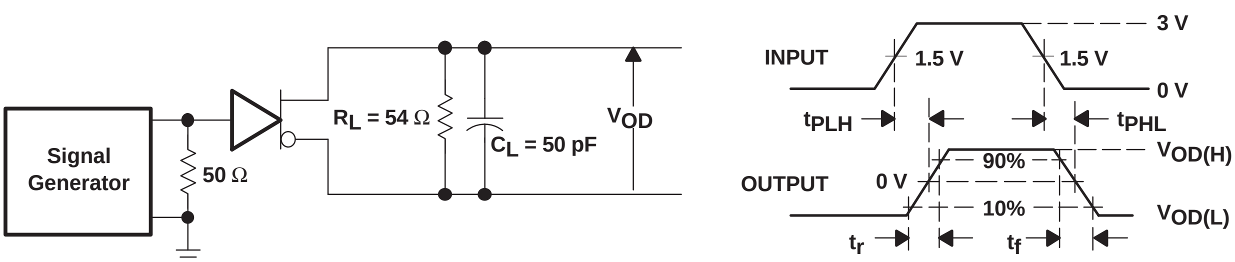


Figure 3. Driver Switching Test Circuit and Waveforms

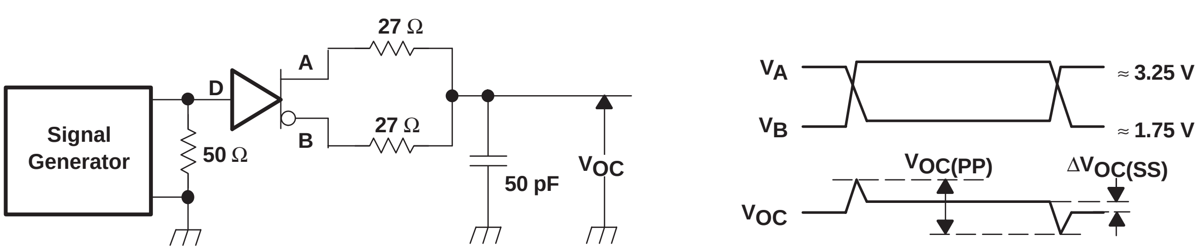
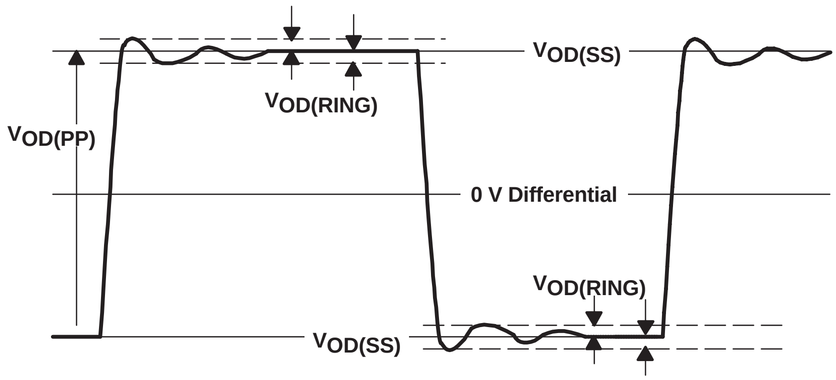


Figure 4. Driver V_{OC} Test Circuit and Waveforms



NOTE: $V_{OD(RING)}$ is measured at four points on the output waveform, corresponding to overshoot and undershoot from the $V_{OD(H)}$ and $V_{OD(L)}$ steady state values.

Figure 5. $V_{OD(RING)}$ Waveform and Definitions

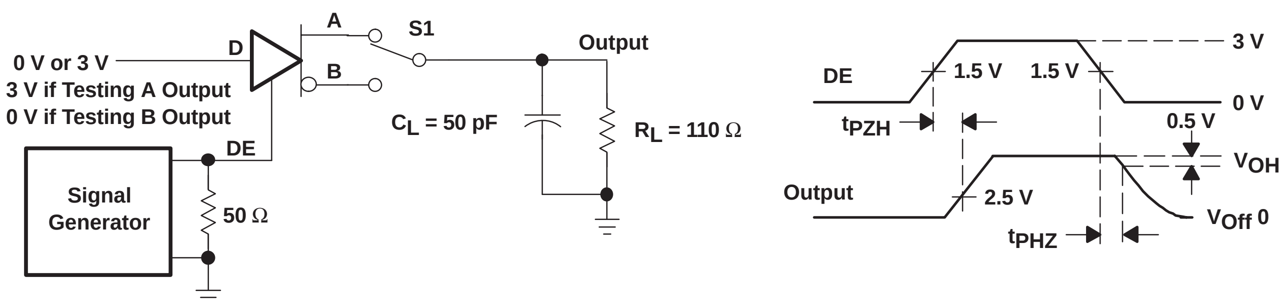


Figure 6. Driver Enable/Disable Test, High Output

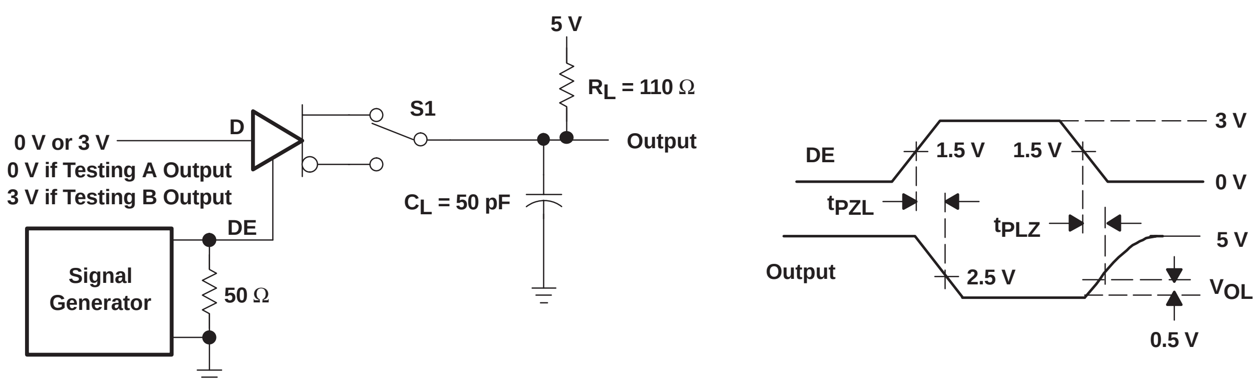


Figure 7. Driver Enable/Disable Test, Low Output

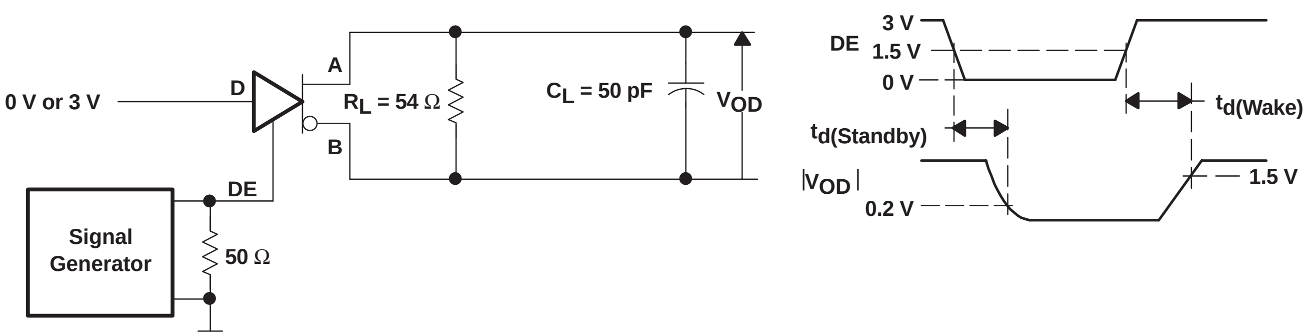


Figure 8. Driver Standby/Wake Test Circuit and Waveforms

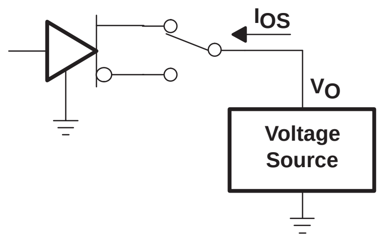


Figure 9. Driver Short-Circuit Test

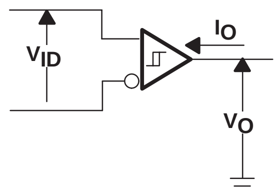


Figure 10. Receiver DC Parameter Definitions

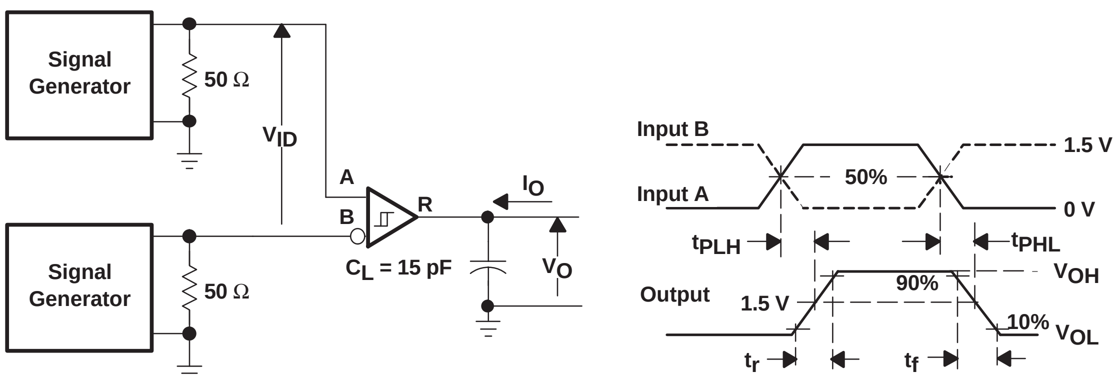


Figure 11. Receiver Switching Test Circuit and Waveforms

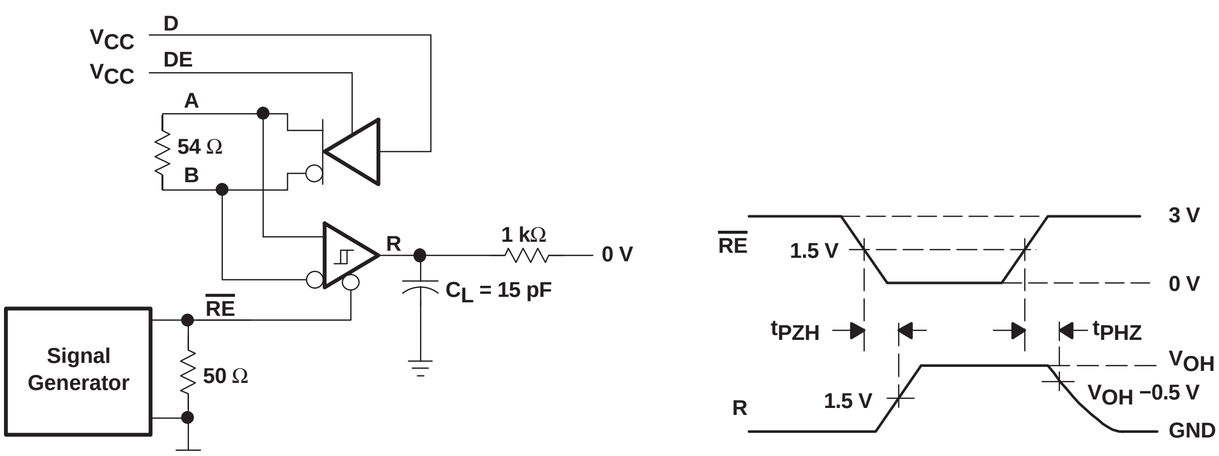


Figure 12. Receiver Enable Test Circuit and Waveforms, Data Output High

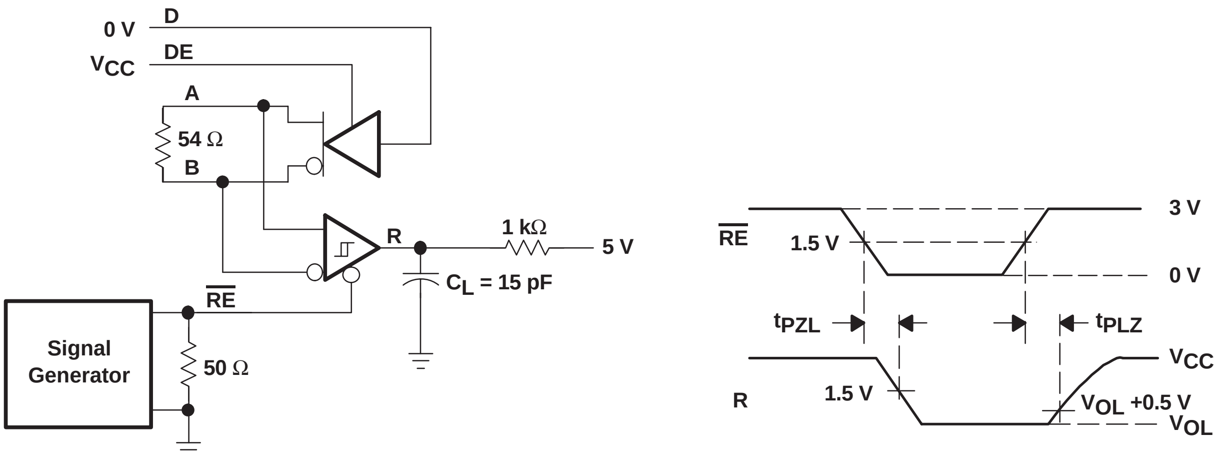


Figure 13. Receiver Enable Test Circuit and Waveforms, Data Output Low

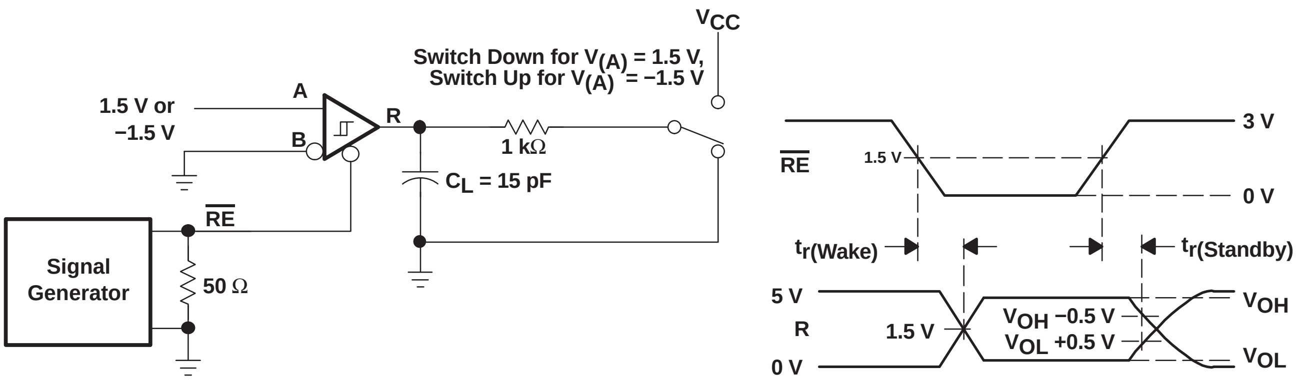


Figure 14. Receiver Standby and Wake Test Circuit and Waveforms

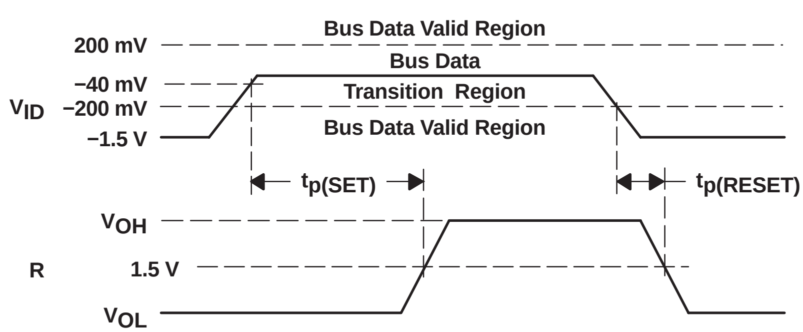


Figure 15. Receiver Active Failsafe Definitions and Waveforms

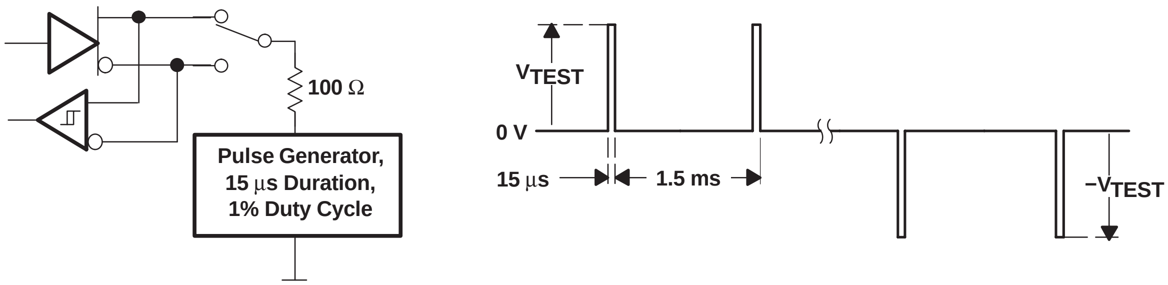
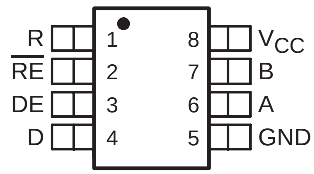


Figure 16. Test Circuit and Waveforms, Transient Overvoltage Test

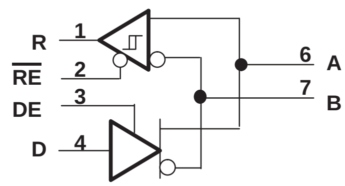
PIN ASSIGNMENTS

D or P PACKAGE
(TOP VIEW)



LOGIC DIAGRAM

POSITIVE LOGIC



TYPICAL CHARACTERISTICS

HVD20, HVD23
BUS PIN CURRENT
vs
BUS PIN VOLTAGE

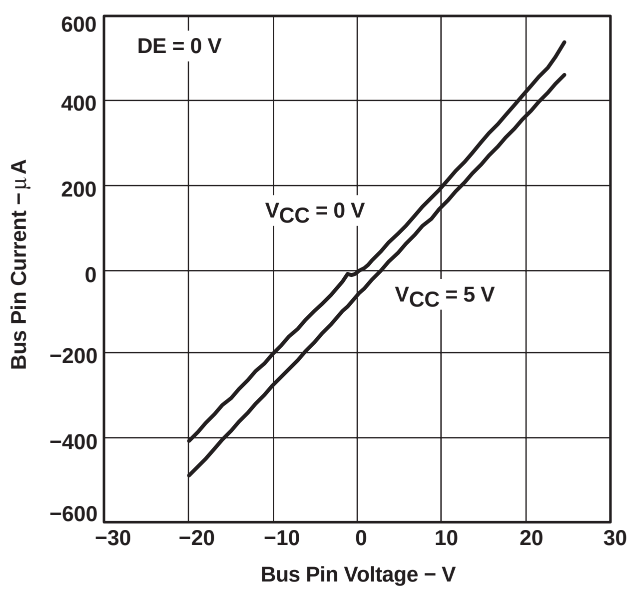


Figure 17

HVD21, HVD22, HVD24
BUS PIN CURRENT
vs
BUS PIN VOLTAGE

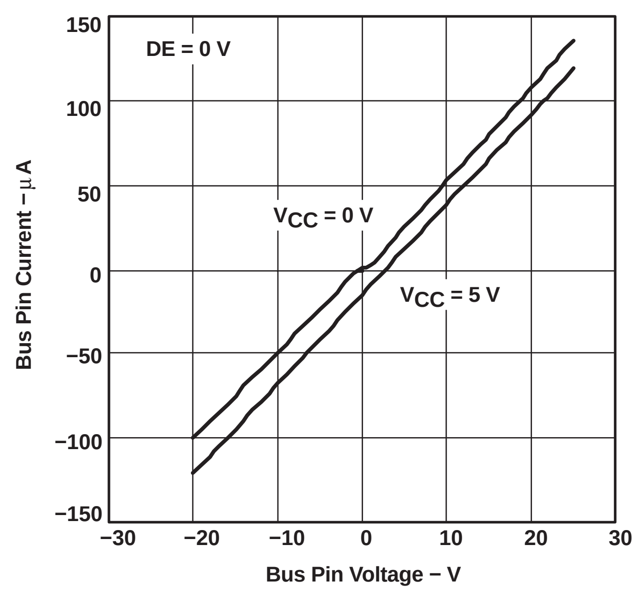


Figure 18

SUPPLY CURRENT
vs
SIGNALING RATE

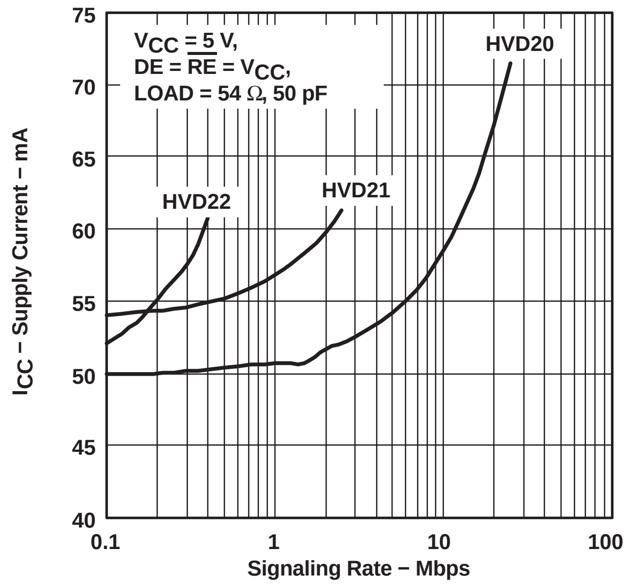


Figure 19

DRIVER DIFFERENTIAL OUTPUT VOLTAGE
vs
DRIVER LOAD CURRENT

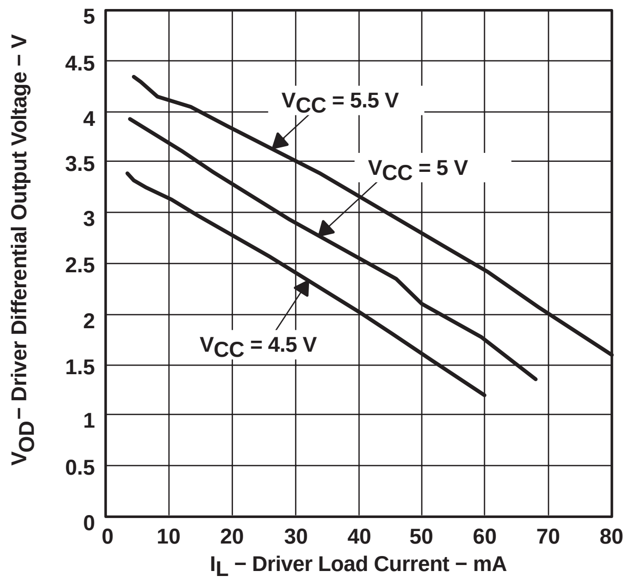


Figure 20

RECEIVER OUTPUT VOLTAGE
vs
DIFFERENTAL INPUT VOLATGE

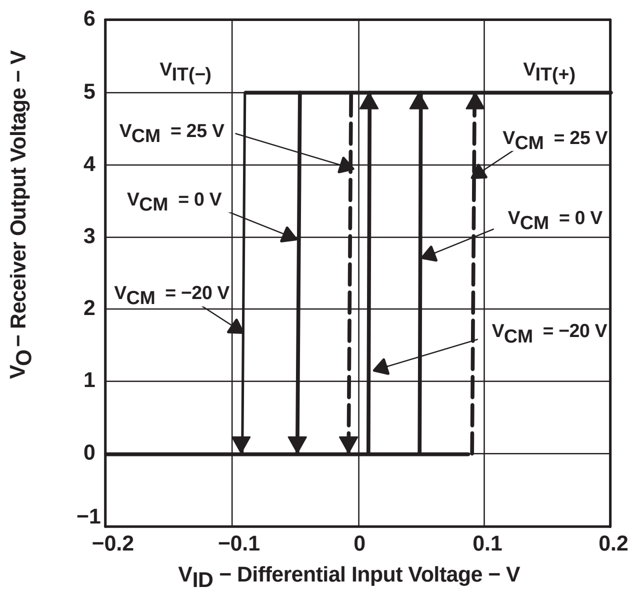


Figure 21

HVD20, HVD23
PEAK-TO-PEAK JITTER
vs
CABLE LENGTH

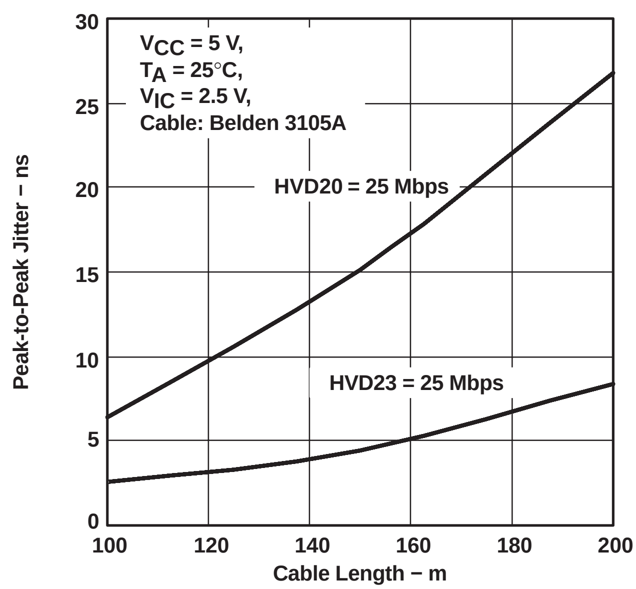


Figure 22

HVD20, HVD21, HVD23, HVD24
PEAK-TO-PEAK JITTER
vs
CABLE LENGTH

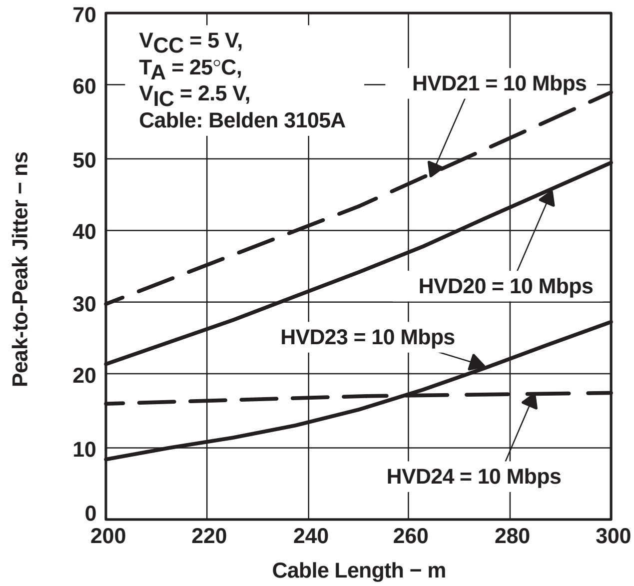


Figure 23

HVD20, HVD23
PEAK-TO-PEAK JITTER
vs
SIGNALING RATE

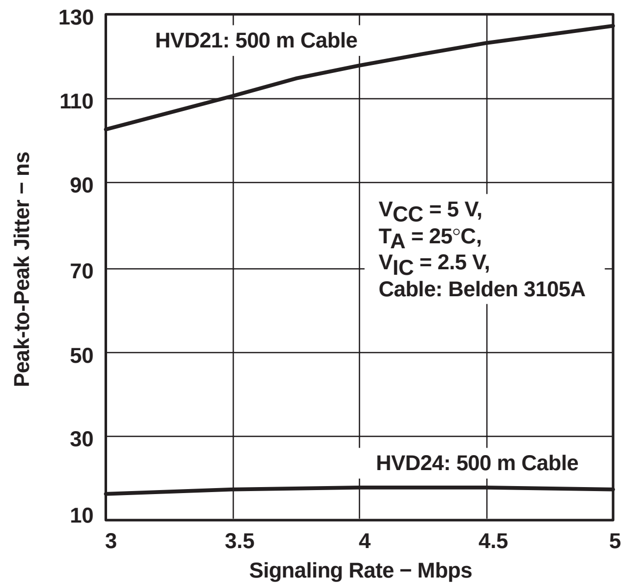


Figure 24

APPLICATION INFORMATION

THEORY OF OPERATION

The HVD2x family of devices integrates a differential receiver and differential driver with additional features for improved performance in electrically-noisy, long-cable, or other fault-intolerant applications.

The receiver hysteresis (typically 130 mV) is much larger than found in typical RS-485 transceivers. This helps reject spurious noise signals which would otherwise cause false changes in the receiver output state.

Slew rate limiting on the driver outputs (SN65HVD21, 22, and 24) reduces the high-frequency content of signal edges. This decreases reflections from bus discontinuities, and allows longer stub lengths between nodes and the main bus line. Designers should consider the maximum signaling rate and cable length required for a specific application, and choose the transceiver best matching those requirements.

When DE is low, the differential driver is disabled, and the A and B outputs are in high-impedance states. When DE is high, the differential driver is enabled, and drives the A and B outputs according to the state of the D input.

When $\overline{RE}$ is high, the differential receiver output buffer is disabled, and the R output is in a high-impedance state. When $\overline{RE}$ is low, the differential receiver is enabled, and the R output reflects the state of the differential bus inputs on the A and B pins.

If both the driver and receiver are disabled, (DE low and $\overline{RE}$ high) then all nonessential circuitry, including auxiliary functions such as failsafe and receiver equalization is placed in a low-power standby state. This reduces power consumption to less than 5 μW. When either enable input is asserted, the circuitry again becomes active.

In addition to the primary differential receiver, these devices incorporate a set of comparators and logic to implement an active receiver failsafe feature. These components determine whether the differential bus signal is valid. Whenever the differential signal is close to zero volts (neither high nor low), a timer initiates, If the differential input remains within the transition range for more than 250 microseconds, the timer expires and set the receiver output to the high state. If a valid bus input (high or low) is received at any time, the receiver output reflects the valid bus state, and the timer is reset.

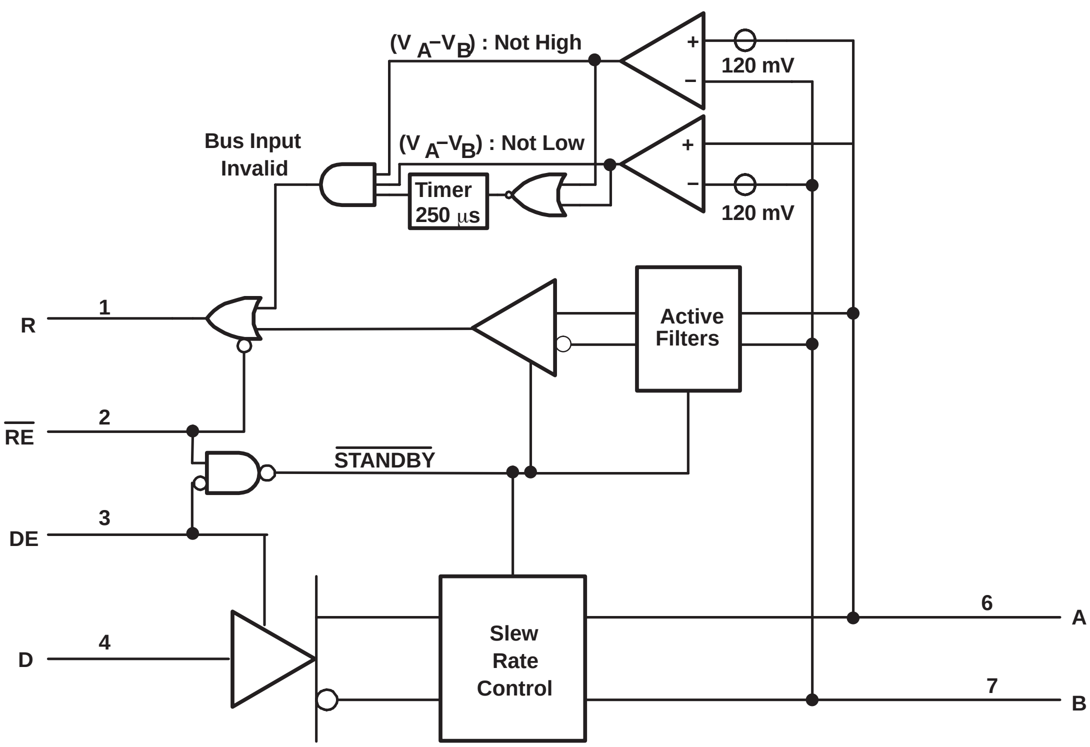


Figure 25. Function Block Diagram

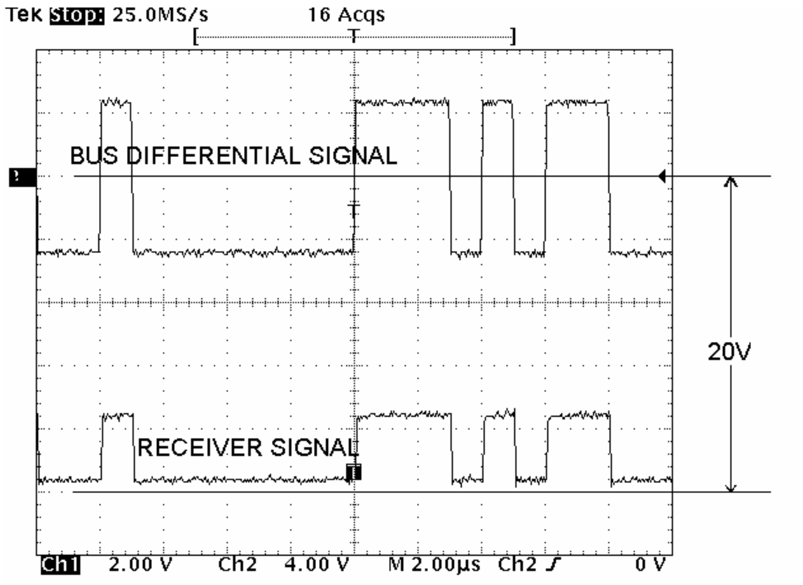


Figure 26. HVD22 Receiver Operation With 20-V Offset on Input Signal

$H(s) = k_0\left[\left(1-k_1\right)+\frac{k_1 p_1}{\left(s+p_1\right)}\right]\left[\left(1-k_2\right)+\frac{k_2 p_2}{\left(s+p_2\right)}\right]\left[\left(1-k_3\right)+\frac{k_3 p_3}{\left(s+p_3\right)}\right]$	k0 (DC loss)	p1 (MHz)	k1	p2 (MHz)	k2	p3 (MHz)	k3
Similar to 160m of Belden 3105A	0.95	0.25	0.3	3.5	0.5	15	1
Similar to 250m of Belden 3105A	0.9	0.25	0.4	3.5	0.7	12	1
Similar to 500m of Belden 3105A	0.8	0.25	0.6	2.2	1	8	1
Similar to 1000m of Belden 3105A	0.6	0.3	1	3	1	6	1

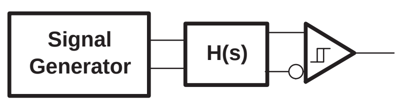


Figure 27. Cable Attenuation Model for Jitter Measurements

INTEGRATED RECEIVER EQUALIZATION USING THE HVD23

Figure 28 illustrates the benefits of integrated receiver equalization as implemented in the HVD23 transceiver. In this test setup, a differential signal generator applied a signal voltage at one end of the cable, which was Belden 3105A twisted-pair shielded cable. The test signal was a pseudo-random bit stream (PRBS) of nonreturn-to-zero (NRZ) data. Channel 1 (top) shows the eye-pattern of the differential voltage at the receiver inputs (after the cable attenuation). Channel 2 (bottom) shows the output of the receiver.

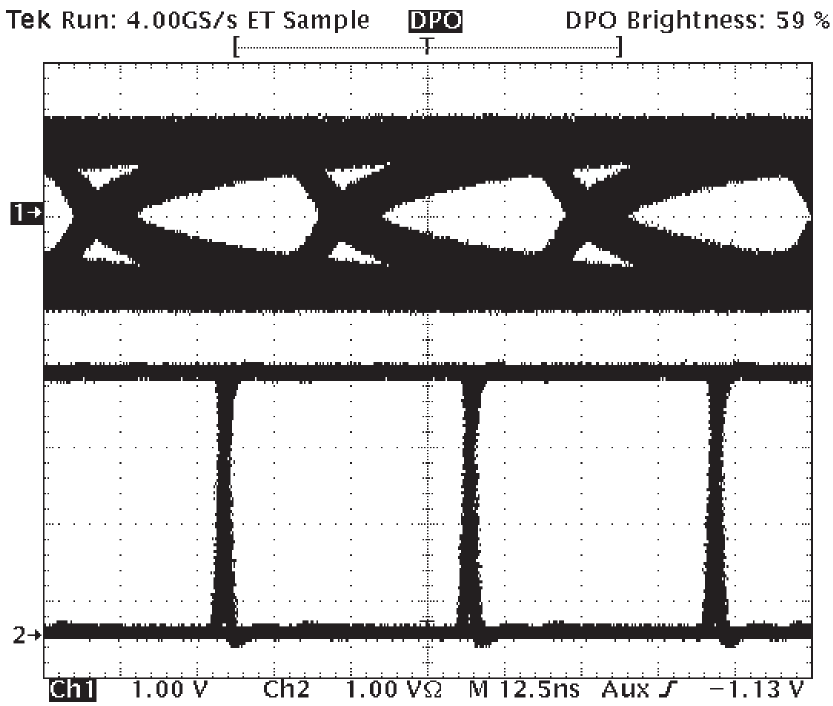


Figure 28. HVD23 Receiver Performance at 25 Mbps Over 150 Meter Cable

INTEGRATED RECEIVER EQUALIZATION USING THE HVD24

Figure 29 illustrates the benefits of integrated receiver equalization as implemented in the HVD24 transceiver. In this test setup, a differential signal generator applied a signal voltage at one end of the cable, which was Belden 3105A twisted-pair shielded cable. The test signal was a pseudo-random bit stream (PRBS) of nonreturn-to-zero (NRZ) data. Channel 1 (top) shows the eye-pattern of the bit stream. Channel 2 (middle) shows the eye-pattern of the differential voltage at the receiver inputs (after the cable attenuation). Channel 3 (bottom) shows the output of the receiver.

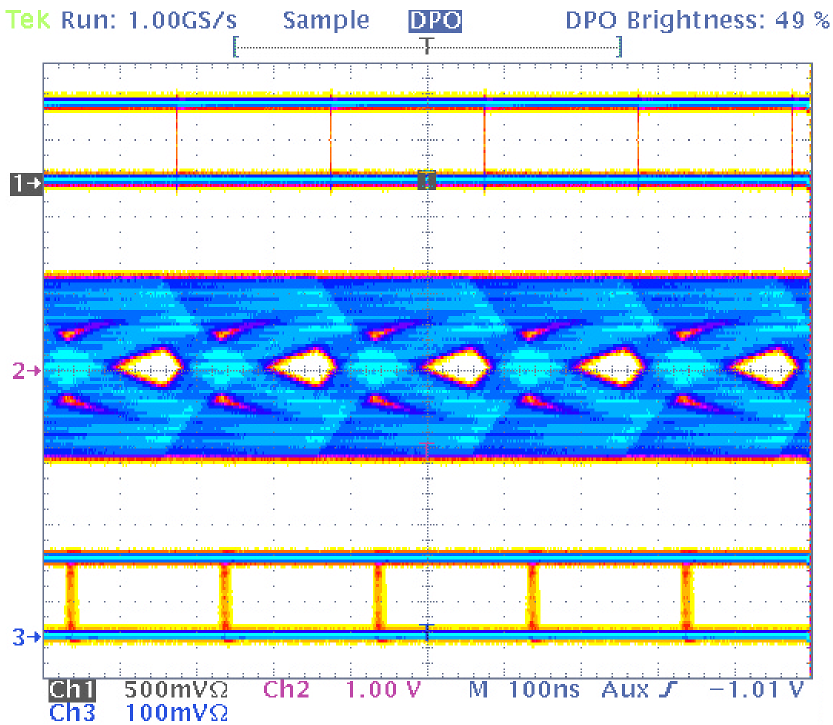


Figure 29. HVD24 Receiver Performance at 5 Mbps Over 500 Meter Cable

NOISE CONSIDERATIONS FOR EQUALIZED RECEIVERS

The simplest way of overcoming the effects of cable losses is to increase the sensitivity of the receiver. If the maximum attenuation of frequencies of interest is 20 dB, increasing the receiver gain by a factor of ten compensates for the cable. However, this means that both signal and noise are amplified. Therefore, the receiver with higher gain is more sensitive to noise and it is important to minimize differential noise coupling to the equalized receiver.

Differential noise is crated when conducted or radiated noise energy generates more voltage on one line of the differential pair than the other. For this to occur from conducted or electric far-field noise, the impedance to ground of the lines must differ.

For noise frequency out to 50 MHz, the input traces can be treated as a lumped capacitance if the receiver is approximately 10 inches or less from the connector. Therefore, matching impedance of the lines is accomplished by matching the lumped capacitance of each.

The primary factors that affect the capacitance of a trace are in length, thickness, width, dielectric material, distance from the signal return path, stray capacitance, and proximity to other conductors. It is difficult to match each of the variables for each line of the differential pair exactly, but a reasonable effort to do so keeps the lines balanced and less susceptible to differential noise coupling.

Another source of differential noise is from near-field coupling. In this situation, an assumption of equal noise-source impedance cannot be made as in the far-field. Familiarly known as crosstalk, more energy from a nearby signal is coupled to one line of the differential pair. Minimization of this differential noise is accomplished by keeping the signal pair close together and physical separation from high-voltage, high-current, or high-frequency signals.

In summary, follow these guidelines in board layout for keeping differential noise to a minimum.

- Keep the differential input traces short.
- Match the length, physical dimensions, and routing of each line of the pair.
- Keep the lines close together.
- Match components connected to each line.
- Separate the inputs from high-voltage, high-frequency, or high-current signals.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN65HVD20D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD20DR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD20P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65HVD21D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD21DR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD21P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65HVD22D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD22DR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD22P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65HVD22PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65HVD23D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD23DR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD23P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65HVD23PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65HVD24D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD24DR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65HVD24P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65HVD24PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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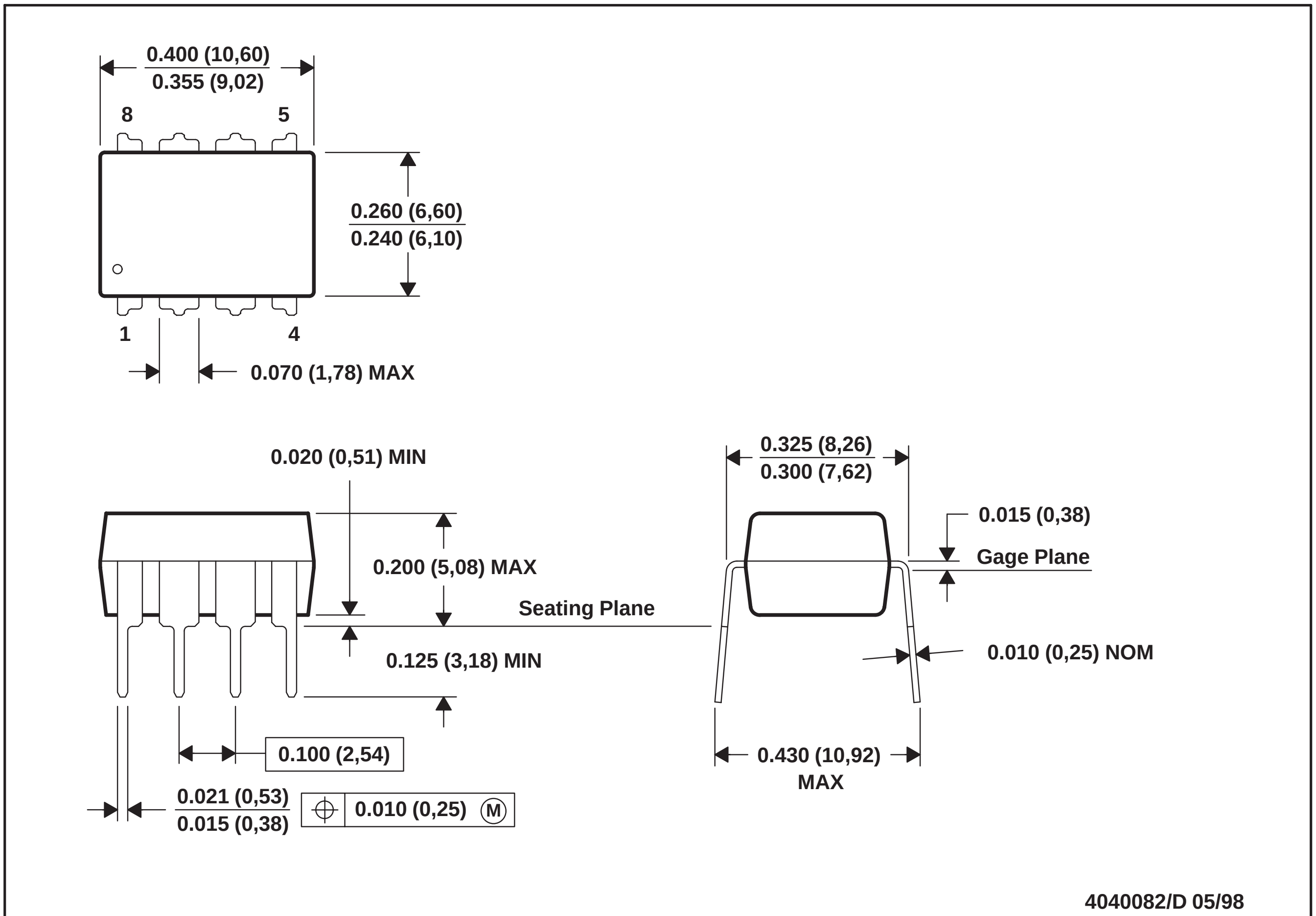
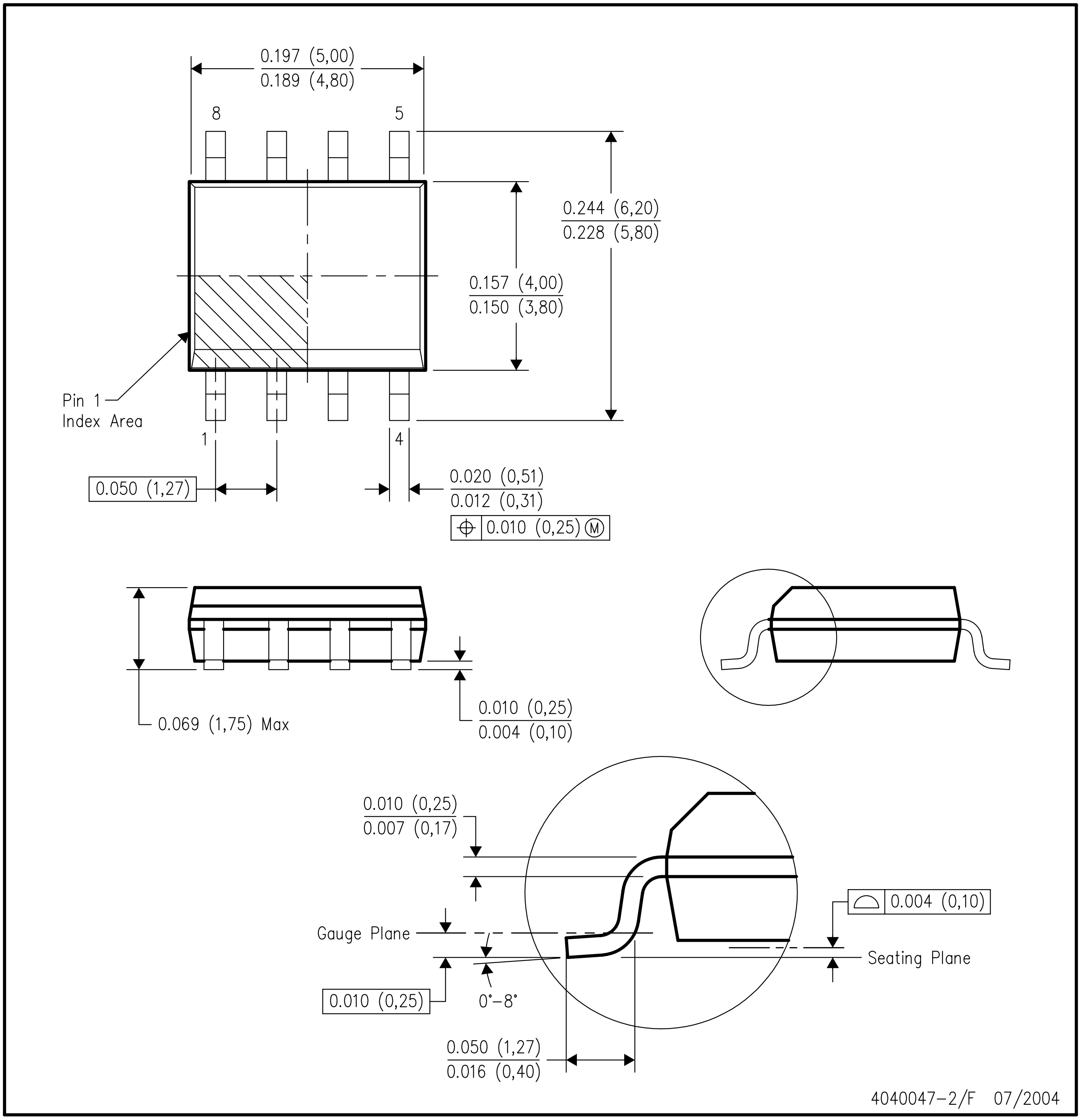


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



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- A. All linear dimensions are in inches (millimeters).
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- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
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